

APSC56-21SRWW SUPER BRIGHT RED

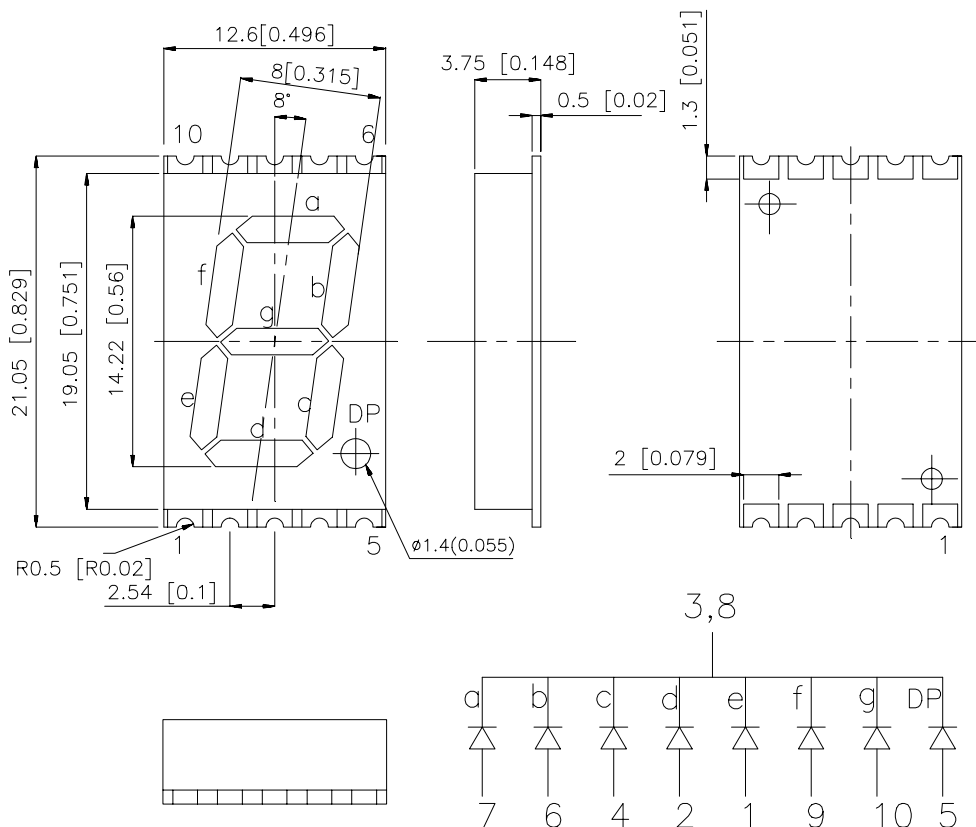
Features

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD: WHITE FACE,WHITE SEGMENT.
- PACKAGE: 500PCS/REEL.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 10 mA		Description
			Min.	Typ.	
APSC56-21SRWW	SUPER BRIGHT RED(GaAlAs)	WHITE DIFFUSED	16	20.8	Common Cathode. Rt.Hand Decimal

Electrical / Optical Characteristics at T_A=25°C

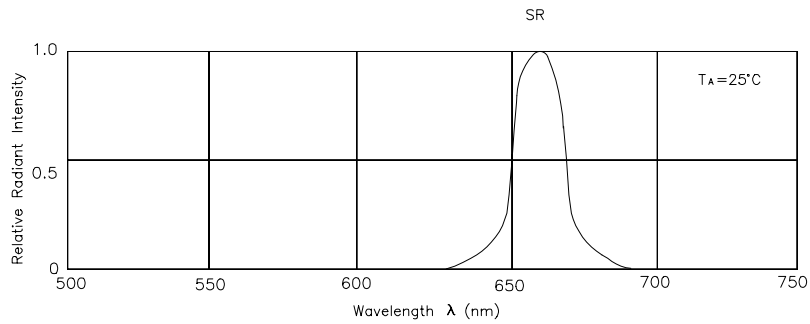
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λ_D	Dominate Wavelength	Super Bright Red	640		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Halfwidth	Super Bright Red	20		nm	IF=20mA
C	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
V _F	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
I _R	Reverse Current	Super Bright Red		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Super Bright Red	Units
Power dissipation	100	mW
DC Forward Current	30	mA
Peak Forward Current [1]	155	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

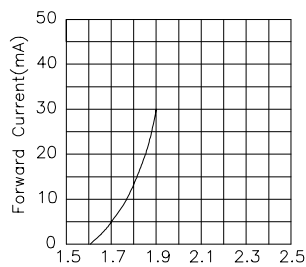
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

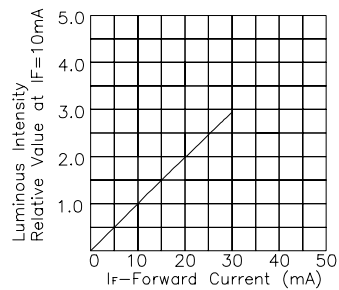


RELATIVE INTENSITY Vs. WAVELENGTH

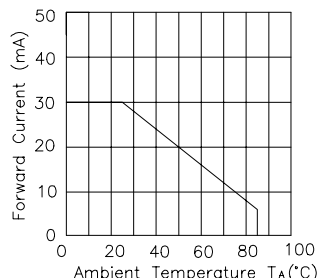
Super Bright Red APSC56-21SRWW



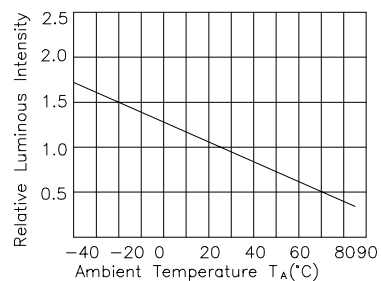
FORWARD CURRENT Vs. FORWARD VOLTAGE



LUMINOUS INTENSITY Vs. FORWARD CURRENT



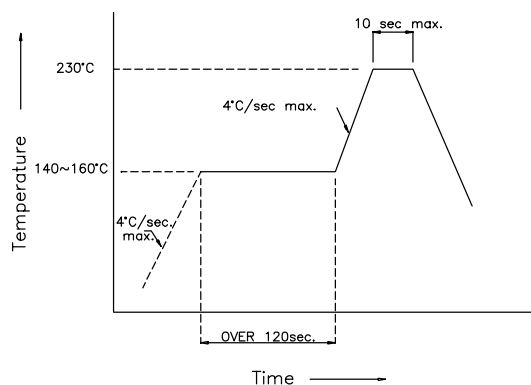
FORWARD CURRENT DERATING CURVE



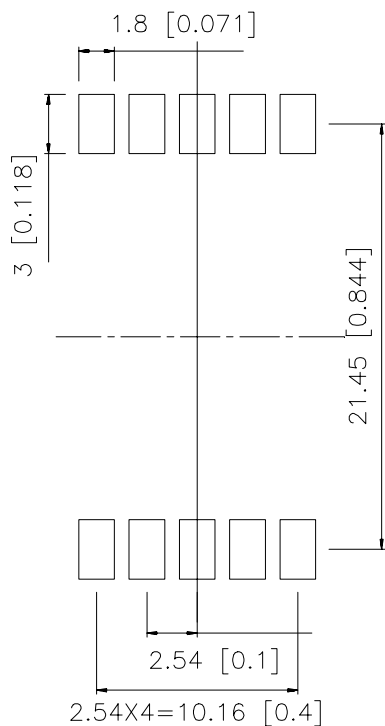
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

APSC56-21SRWW SMT Reflow Soldering Instruction

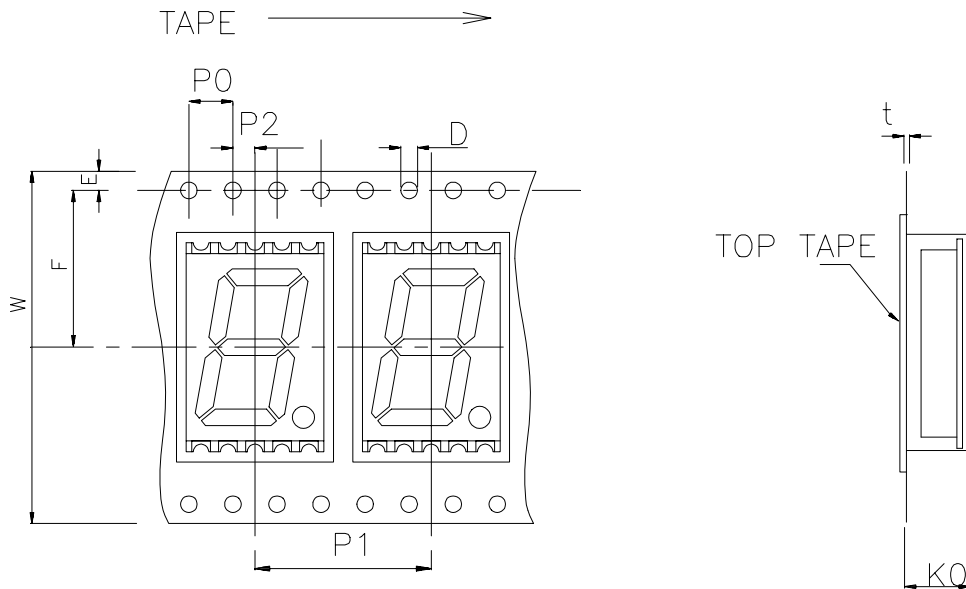
Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specification
(Units : mm)



DIMENSIONS PER MILLIMETRES(INCHES)	
D	1.55[0.06]±0.05
E	1.75±0.1(.069)
F	14.2[0.559]±0.1
P	16[0.63]TYP.
P0	4.0(.157)TYP.
P2	2.0(.079±0.02)TYP.
t	0.3[0.012]TYP.
K0	4(0.157)±0.1
W	32[1.26]±0.3